



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**Notification# 20170117004  
Datasheet for TLV2217  
Information Only**

**Date:** February 17, 2017  
**To:** PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services

**Information Only  
Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TLV2217-33KCSE3	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20170117004	<b>PCN Date:</b>	Feb. 17, 2017
<b>Title:</b>	Datasheet for TLV2217		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

### Notification Details

#### Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



**TLV2217**

SLVS067M – MARCH 1992 – REVISED NOVEMBER 2016

#### Changes from Revision L (April 2005) to Revision M

**Page**

• Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section .....	1
• Deleted Ordering Information table; see Package Ordering Addendum at the end of the data sheet .....	1
• Changed Junction-to-ambient thermal resistance, $R_{\theta JA}$ , values in Thermal Information table From: 83°C/W To: 81.6°C/W (PW), From: 28°C/W To: 31°C/W (KVU), and From: 19°C/W To: 22.5°C/W (KCS).....	4
• Changed Junction-to-case (top) thermal resistance, $R_{\theta JC(top)}$ , values in Thermal Information table From: 32°C/W To: 22.1°C/W (PW), From: 19°C/W To: 37.5°C/W (KVU), and From: 17°C/W To: 34.6°C/W (KCS).....	4
• Changed Junction-to-case (bottom) thermal resistance, $R_{\theta JC(bot)}$ , values in Thermal Information table From: 1.4°C/W To: 0.6°C/W (KVU) and From: 3°C/W To: 0.8°C/W (KCS).....	4

The datasheet number will be changing.

Device Family	Change From:	Change To:
TLV2217	SLVS067L	SLVS067M

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TLV2217>

#### Reason for Change:

To accurately reflect device thermal characteristics.

#### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

#### Changes to product identification resulting from this PCN:

None.

#### Product Affected:

TLV2217-18KCS	TLV2217-18KCSE3	TLV2217-18KVURG3	TLV2217-25KCSE3
TLV2217-25KVURG3	TLV2217-25PWR	TLV2217-33KCSE3	TLV2217-33KVURG3
TLV2217-33PWR			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>